

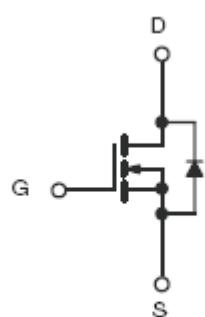
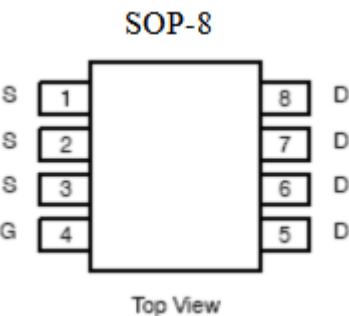
1. Features

- Advanced trench process technology
- High density cell design for ultra low on-resistance
- Fully characterized avalanche voltage and current

2. Applications

- $V_{ds}=30V$
- $R_{DS(ON)}=9.0\text{m}\Omega(\text{typ.}), V_{GS}@10V, I_{ds}@12A$
- $R_{DS(ON)}=11.5\text{m}\Omega(\text{typ.}), V_{GS}@4.5V, I_{ds}@6A$

3. Pin configuration



Pin	Function
1,2,3	Source
4	Gate
5,6,7,8	Drain

4. Maximum ratings and thermal characteristics

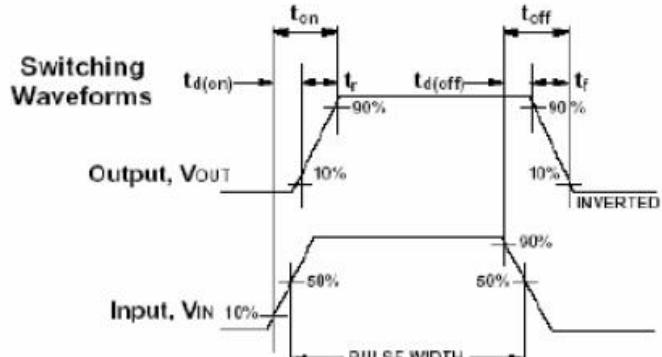
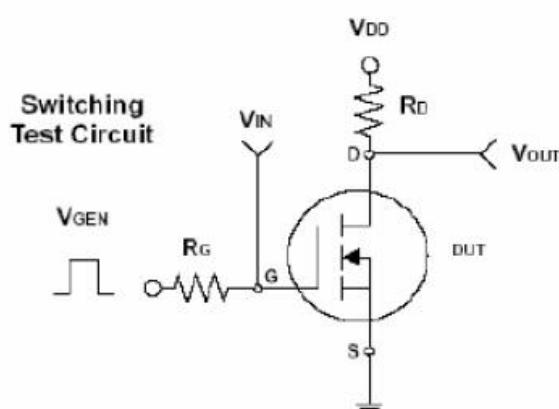
(Ta=25°C,unless otherwise notes)				
Rating	Symbol	Value	Unit	
Drain-source voltage	V _{DS}	30	V	
Gate-source voltage	V _{GS}	± 20	V	
Continuous drain current	I _D	12	A	
Pulsed drain current ¹⁾	I _{DM}	48	A	
Maximum power dissipation	T _A =25°C	P _D	3.1	W
	T _A =75°C	P _D	2.0	W
Operating junction and storage temperature range	T _J /T _{STG}	-55 to 150	°C	
Junction-to-case thermal resistance	R _{θJC}	40.3	°C/W	
Junction-to ambient thermal resistance (PCB mount) ²⁾	R _{θJA}	59	°C/W	

Note:Repetitive rating:pulse width limited by the maximum junction temperature

5. Ordering information

Part number	Package
KNE6306A	SOP-8

6. Typical application circuit



7. Electrical characteristics

(Ta=25°C,unless otherwise notes)

Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Units
Static						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V,I _D =250μA	30	-	-	V
Drain-source on-state resistance(m)	R _{DS(ON)}	V _{GS} =4.5V,I _D =6A	-	11.5	14.0	mΩ
		V _{GS} =10V,I _D =12A	-	8.0	10.0	mΩ
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	1	1.8	3	V
Forward transconductance	G _f	V _{DS} =15V,I _D =6A	-	12	-	S
Zero gate voltage drain current	I _{DSS}	V _{DS} =25V,V _{GS} =0V	-	-	1	μA
Gate-source forward leakage	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
Dynamic³⁾						
Total gate charge	Q _g	I _D =35A V _{DS} =15V V _{GS} =10V	-	10		nC
Gate-source charge	Q _{gs}			3.5		nC
Gate-drain (“miller”)charge	Q _{gd}		-	3		nC
Turn-on delay time	t _{d(off)}	V _{DD} =15V I _D =1A R _G =6Ω R _L =15Ω V _{GEN} =10V	-	12	-	ns
Rise time	t _r		-	4	-	ns
Turn-off delay time	t _{d(off)}		-	32	-	ns
Fall time	t _f		-	6	-	ns
Input capacitance	C _{iss}	V _{GS} =0V V _{DS} =15V f=1.0MHz	-	1300	-	pF
Output capacitance	C _{oss}		-	270	-	pF
Reverse transfer capacitance	C _{rss}		-	145	-	pF

Source-drain diode

Parameter	Symbol	Test condition	Min.	Typ.	Max.	Units
Diode forward voltage	V _{SD}	I _s =10A,V _{GS} =0V	-	0.87	1.5	V
Max.diode forward current	I _s		-	-	12	A

Notes:Pulse width≤300μs,duty cycle≤2%

8. Test circuits and waveforms

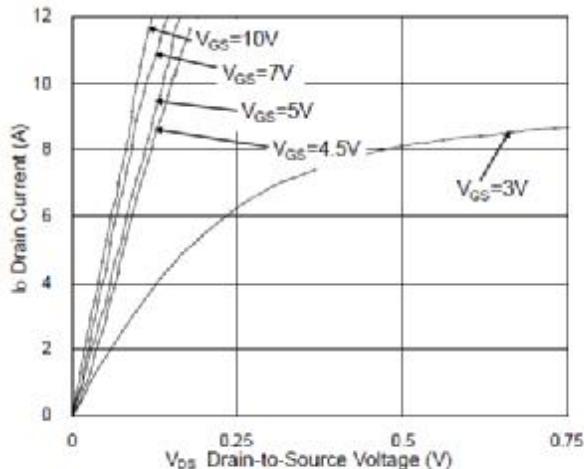


Fig.1 Typical Output Characteristics

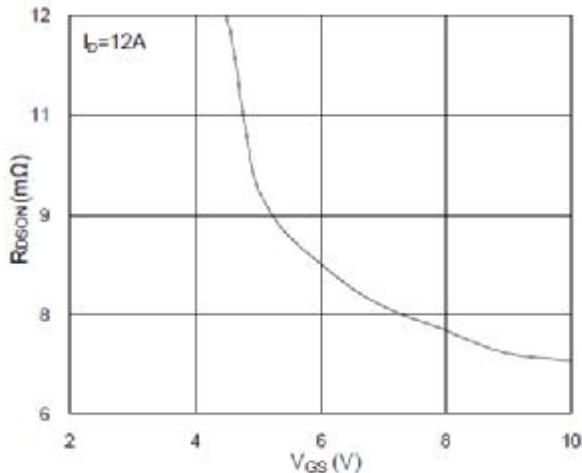


Fig.2 On-Resistance vs. G-S Voltage

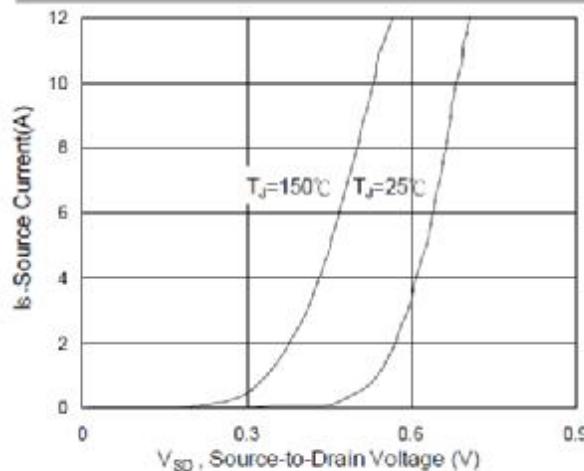


Fig.3 Forward Characteristics of Reverse

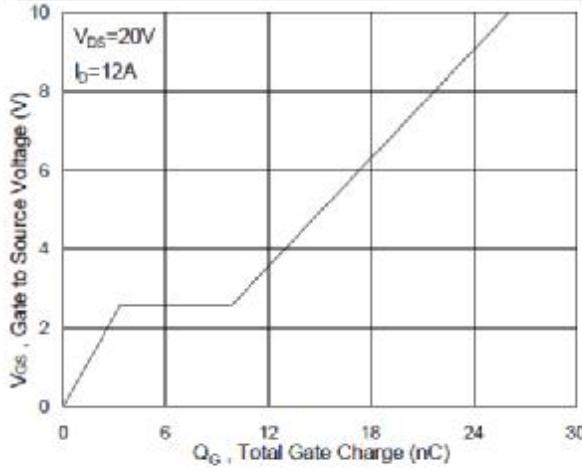


Fig.4 Gate-Charge Characteristics

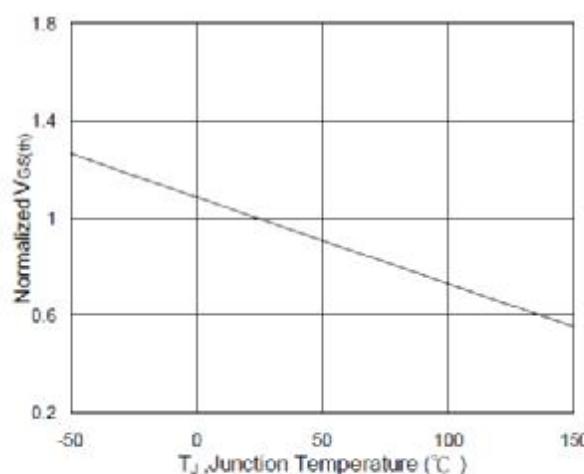


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

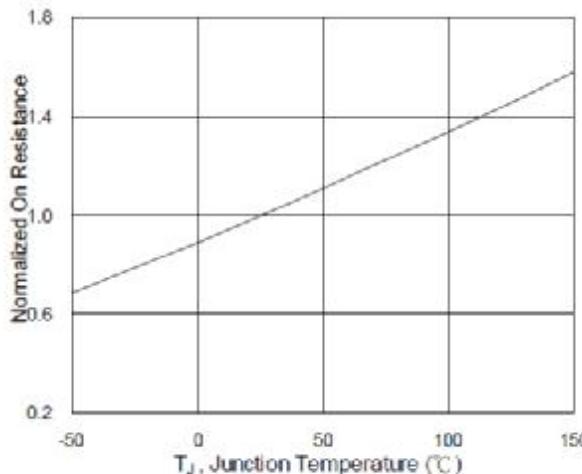


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

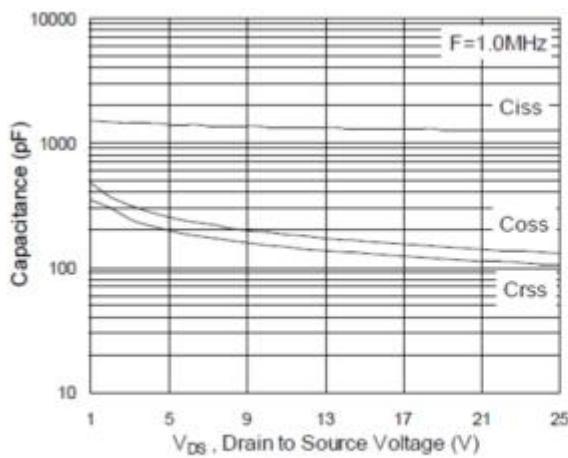


Fig.7 Capacitance

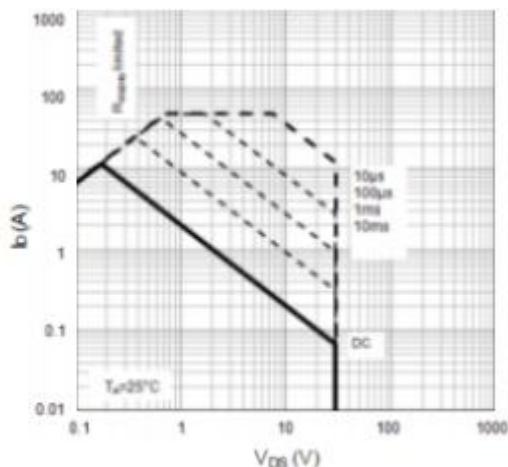


Fig.8 Safe Operating Area

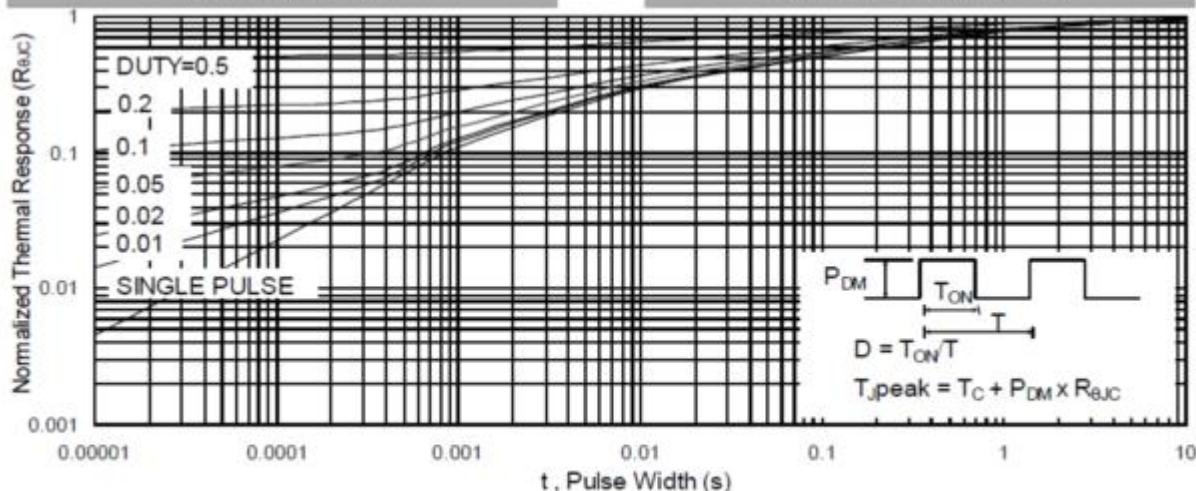


Fig.9 Normalized Maximum Transient Thermal Impedance

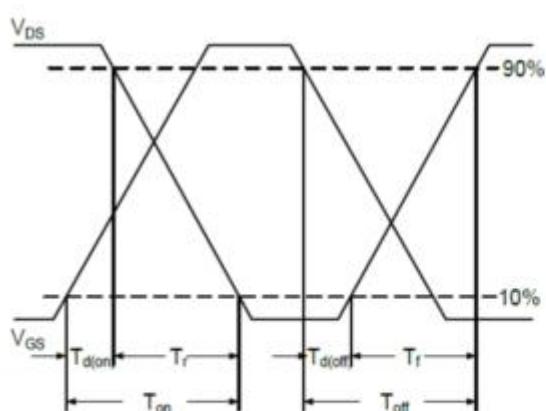


Fig.10 Switching Time Waveform

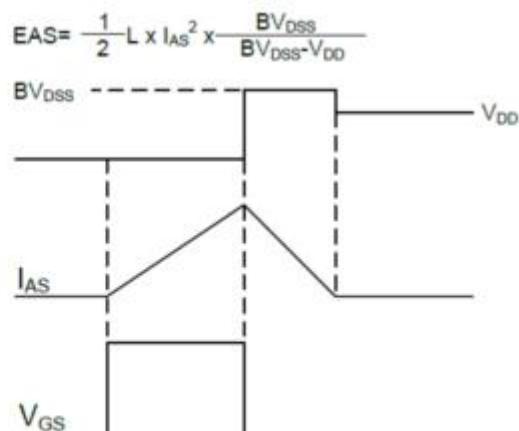


Fig.11 Unclamped Inductive Switching Waveform